







(2.00 mm) .0787"

**HDAM, HDAF SERIES** 

# **RUGGED ELEVATED HIGH-DENSITY ARRAY**

**HDAM Mates with:** 

**HDAF** 

**HDAF Mates with:** 

HDAM

## **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM or www.samtec.com?HDAF

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Current Rating:
3.4 A per pin
(6 adjacent pins powered)
Operating Temp Range:
-55 °C to +125 °C
Contact Resistance: 19 mΩ
Working Voltage: 200 VAC
Mated Cycles: 100
RoHS Compliant: Yes
Lead-Free Solderable: Yes

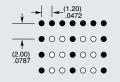
### RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



#### NO. OF ROWS NO. OF PINS PLATING SOLDER LEAD OTHER **HDAM TYPE PER ROW** STYLE OPTION OPTION -S .P = 30 µ" 15, Specify -2 = Pick & -23-13(0.76 µm) = Lead-Free **LEAD** Place Pad Gold on Tin Alloy **STYLE** contact area 95.5% Sn/ from Matte Tin 3.8% Ag/ on tails and chart 0.7% Cu guide pins Solder Charge (22.50) .886 -LEAD (14.41) .567 -12.0No. of No. of Pins (19.41) .764 Pins Per Row -17.0 Per Row (2.00) .0787 x (2.00) .0787 (2.00) .0787 **RUGGEDIZED** (16.06) (11.55) Integrated guide posts **←** (5.09) .200

## DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

\*2:1 S:G Ratio

## ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other platings
   Contact Samtec.

**Note:** HD Mezz is a trademark of Molex Incorporated

**Note:** Some lengths, styles and options are non-standard, non-returnable.

